

# **BL 2012 Series (Preliminary)**

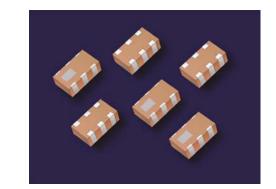
## **Multilayer Chip Baluns**

## **Features**

Monolithic SMD with small, low-profile and light-weight type.

## **Applications**

❖0.8 ~ 6 GHz wireless communication systems, including DECT/PACS/PHS/GSM/DCS phones, WLAN card, Bluetooth modules, etc.



## **Specifications**

Part Number	Frequency Range (MHz)	Unbalanced Impedance (ohm)	Balanced Impedance (ohm)	Insertion Loss (dB)	VSWR @BW	Phase Difference (degree)	Amplitude Difference (dB)
BL2012- 20B0869_	824 ~ 915	50	200	1.5 max.	2.0 max.	180 ± 10	2.0 max.

Q'ty/Reel (pcs) : 4000 Operating Temperature Range : -40 ~ +85 °C Storage Temperature Range : -40 ~ +85 °C Storage Period : 12 months max.\*

\*12 months in vacuum sealed bag and 1 week after opened. Please keep unused parts in vacuum sealed bags.

Solder Paste : SAC 305 type is recommended.

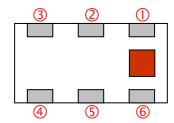
Power Capacity : 2W max.

## **Part Number**

<u>BL</u>	<u>2012</u>	-	<u> 20</u>	<u>B</u>	<u>0869</u>		<u>/LF</u>
1	2		3	<u>(4)</u>	(5)	6	7

① Type	BL : Balun	② Dimensions (L×W)	2.0 × 1.25 mm
3 Balanced Impedance	20 : 200 ohm	Specification Code	В
© Central Frequency	0869 : 869MHz	© Packaging	T: Tape & Reel B: Bulk
Soldering = lead-contain /LF=lead-free			

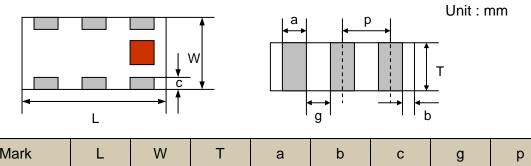
## **Terminal Configuration**



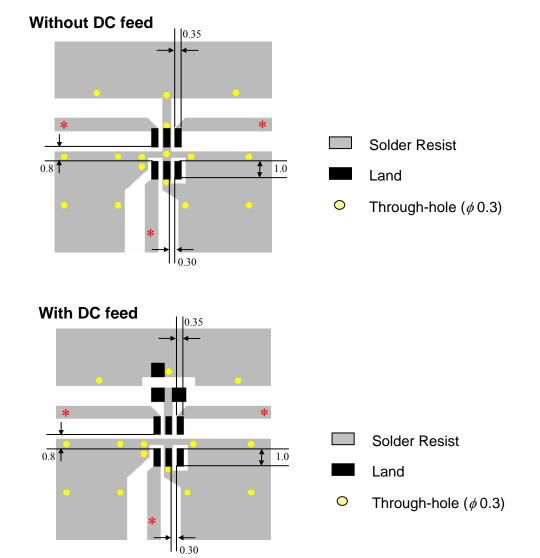
No.	Terminal Name	No.	Terminal Name
1	Unbalanced Port (IN)	4	Balanced Port (OUT2)
2	GND or DC feed + RF GND	(5)	GND
3	Balanced Port (OUT1)	6	NC



## **Dimensions and Recommended PC Board Pattern**



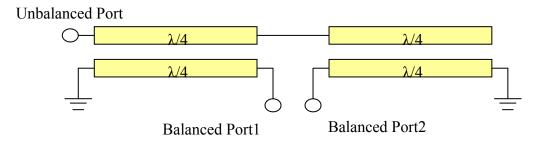
Mark	L	W	T	а	b	С	g	р
Dimensions	2.0 ±	1.25 ±	0.70 ±	0.3 ±	0.2 ±	0.3+0.1	0.35 ±	0.65 ±
	0.1	0.1	0.1	0.1	0.1	/-0.2	0.1	0.05



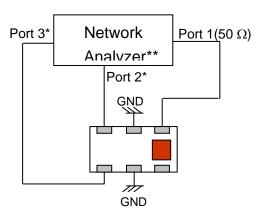
- \* Line width should be designed to match  $50\Omega$  characteristic impedance, depending on PCB material and thickness.
- \*\* By-pass capacitor should be connected when feeding DC power.



## **Equivalent Circuit**



## **Measuring Diagram**



Port 1:Unbalanced Port

Ports 2 and 3: Balanced Port

IL=S<sub>ds21</sub>

RL=S<sub>ss11</sub>

 $Amp\_balance = dB(S(2,1)/S(3,1))$ 

Phase\_balance = Phase(S(2,1)/S(3,1))

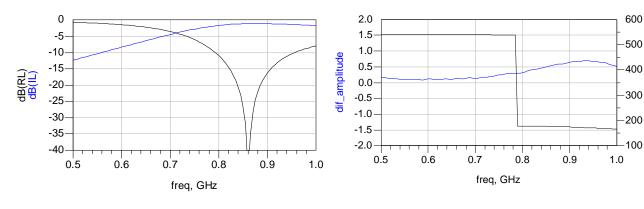
\*Impedance for ports 2 and 3 = Balanced Impedance/2

\*\*E5071B from Agilent

## Typical Electrical Characteristics (T=25°C)

## **Insertion and Return Loss**

## **Amplitude and Phase Balance**



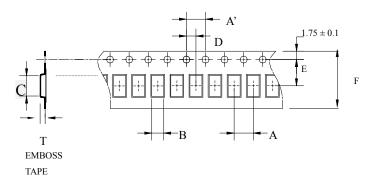
#### **Notes**

❖The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.



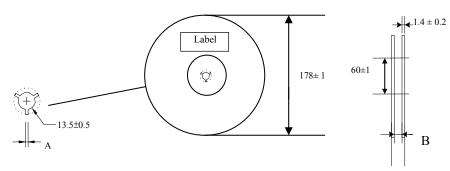
## **Taping Specifications**

## **❖Tape Dimensions (Unit: mm) & Quantity**



Туре	Α	A'	В	С	D	E	F	Т	Quantity/reel	Tape material
2012	4.0±	4.0±	1.35±	2.15±	2.0±	3.5±	8.0±	1.00±	4,000pcs	Plastic
2012	0.1	0.1	0.05	0.05	0.05	0.1	0.1	0.05	4,000pcs	(Embossed)

### ❖Reel Dimensions (Unit: mm)



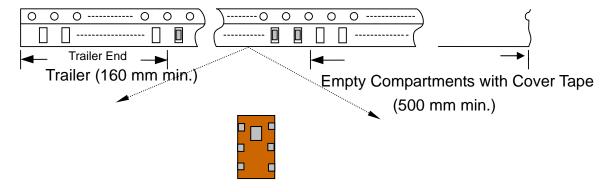
Label: Customer's Name,

ACX P/N, Q'ty, Date,

ACX Corp.

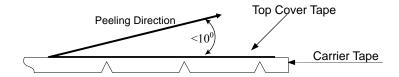
Туре	Α	В		
2012	2.3±0.5	9.0±0.3		

#### **❖Leader and Trailer Tape**





#### **❖Peel-off Force**



Peel-off force should be in the range of 0.1-0.6~N at a peel-off speed of  $300\pm10~mm/min$ .

## **❖Storage Conditions**

- (1) Temperature:  $+5 \sim 35^{\circ}$ C, relative humidity (RH):  $45 \sim 75\%$ .
- (2) Non-corrosive environment

#### **Notes**

The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.



## **Mechanical & Environmental Characteristics**

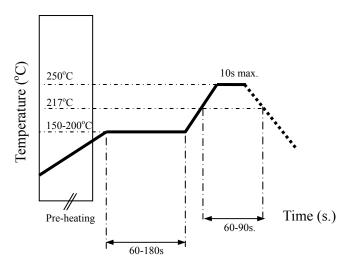
Item		Requirements	Procedure
Solderability	1. 2.	No apparent damage More than 75% of the terminal electrode shall be covered with new solder	<ol> <li>Preheat: 120± 5 °C</li> <li>Solder: 245± 5 °C for 5± 1 sec</li> </ol>
Soldering strength (Termination Adhesion)	1.	1kg minimum	<ol> <li>Solder specimen onto test jig.</li> <li>Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction</li> </ol>
Deflection (Substrate Bending)	1. 2.	No apparent damage Fulfill the electrical specification	<ol> <li>Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile.</li> <li>Apply a bending force of 2mm deflection</li> </ol> Pressure Rod R230 90mm
Heat/Humidity Resistance	1. 2.	No apparent damage Fulfill the electrical specification after test	<ol> <li>Temperature: 85± 2°C</li> <li>Humidity: 90% ~ 95% RH</li> <li>Duration: 1000±48hrs</li> <li>Recovery: 1-2hrs</li> </ol>
Thermal shock (Temperature Cycle)	1. 2.	No apparent damage Fulfill the electrical specification after test	1. One cycle/step 1: 125 ± 5°C for 30 min step 2: - 40 ± 5°C for 30 min 2. No of cycles: 100 3. Recovery:1-2 hrs
Low Temperature Resistance	1. 2.	No apparent damage Fulfill the electrical specification after test	<ol> <li>Temperature: -40°± 5 °C</li> <li>Duration: 500 ±24hrs</li> <li>Recovery: 1-2hrs</li> </ol>



## **Soldering Conditions**

**❖** Typical Soldering Profile for Lead-free Process

Reflow Soldering:



#### **Notes**

❖The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

## **Advanced Ceramic X Corp.**

16 Tzu Chiang Road, Hsinchu Industrial District Hsinchu Hsien 303, Taiwan TEL:886-3-5987008 FAX:886-3-5987001

E-mail: <a href="mailto:acx@acxc.com.tw">acx@acxc.com.tw</a>
http://www.acxc.com.tw